

# HD74LS266

Quadruple 2-input Exclusive-NOR Gates  
(with open collector outputs)

REJ03D0472-0200

Rev.2.00

Feb.18.2005

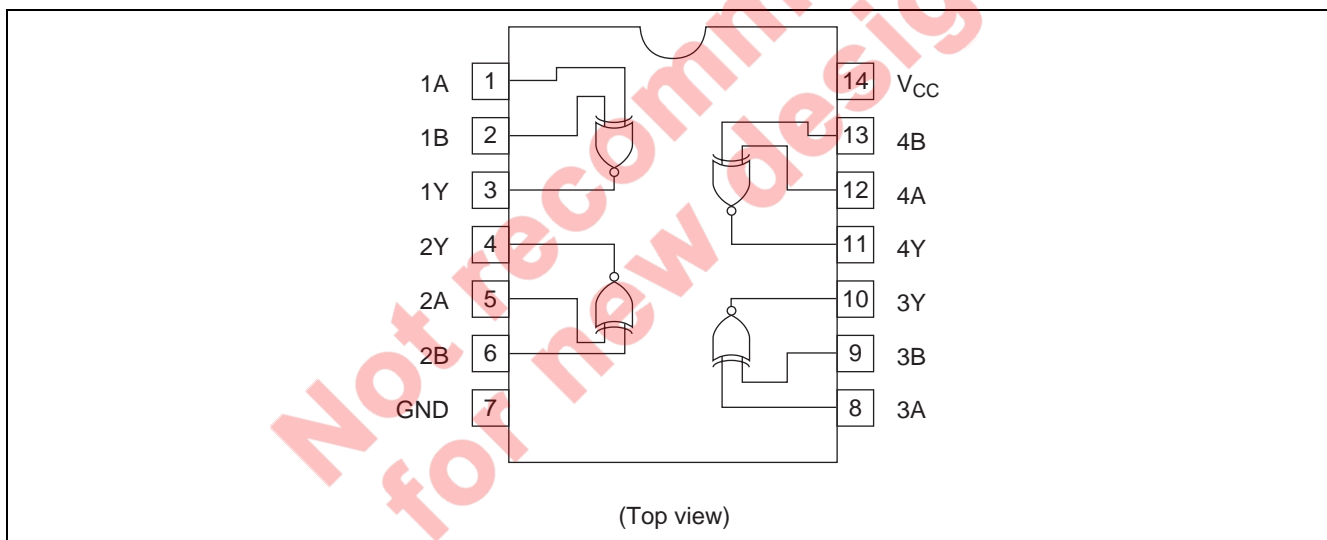
## Features

- Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LS266P	DILP-14 pin	PRDP0014AB-B (DP-14AV)	P	—
HD74LS266FPEL	SOP-14 pin (JEITA)	PRSP0014DF-B (FP-14DAV)	FP	EL (2,000 pcs/reel)

Note: Please consult the sales office for the above package availability.

## Pin Arrangement



## Function Table

Inputs		Output
A	B	Y
L	L	H
L	H	L
H	L	L
H	H	H

H; high level, L; low level

## Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage	$V_{CC}$	7	V
Input voltage	$V_{IN}$	7	V
Power dissipation	$P_T$	400	mW
Storage temperature	$T_{stg}$	-65 to +150	°C

Note: Voltage value, unless otherwise noted, are with respect to network ground terminal.

## Recommended Operating Conditions

Item	Symbol	Min	Typ	Max	Unit
Supply voltage	$V_{CC}$	4.75	5.00	5.25	V
Output voltage	$V_{OH}$	—	—	5.5	V
Output current	$I_{OL}$	—	—	8	mA
Operating temperature	$T_{opr}$	-20	25	75	°C

## Electrical Characteristics

( $T_a = -20$  to  $+75$  °C)

Item	Symbol	min.	typ.*	max.	Unit	Condition
Input voltage	$V_{IH}$	2.0	—	—	V	
	$V_{IL}$	—	—	0.8		
Output current	$I_{OH}$	—	—	100	$\mu A$	$V_{CC} = 4.75$ V, $V_{IH} = 2$ V, $V_{IL} = 0.8$ V, $V_{OH} = 5.5$ V
Output voltage	$V_{OL}$	—	—	0.4	V	$V_{CC} = 4.75$ V, $V_{IH} = 2$ V, $V_{IL} = 0.8$ V
		—	—	0.5		
Input current	$I_{IH}$	—	—	40	$\mu A$	$V_{CC} = 5.25$ V, $V_I = 2.7$ V
	$I_{IL}$	—	—	-0.8	mA	$V_{CC} = 5.25$ V, $V_I = 0.4$ V
	$I_I$	—	—	0.2	mA	$V_{CC} = 5.25$ V, $V_I = 7$ V
Supply current	$I_{CC}^{**}$	—	8	13	mA	$V_{CC} = 5.25$ V
Input clamp voltage	$V_{IK}$	—	—	-1.5	V	$V_{CC} = 4.75$ V, $I_{IN} = -18$ mA

Notes: \*  $V_{CC} = 5$  V,  $T_a = 25$  °C

\*\*  $I_{CC}$  is measured with one input of each gate at 4.5 V, the other inputs grounded, and the outputs open.

## Switching Characteristics

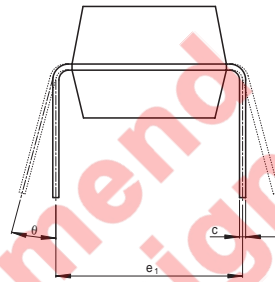
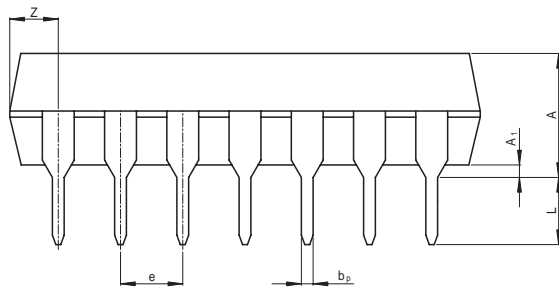
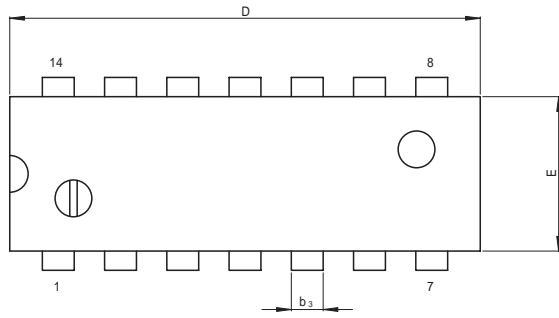
( $V_{CC} = 5$  V,  $T_a = 25$  °C)

Item	Symbol	Inputs	min.	typ.	max.	Unit	Condition
Propagation delay time	$t_{PLH}$	A or B	—	18	30	ns	$C_L = 15$ pF, $R_L = 2$ k $\Omega$
	$t_{PHL}$		—	18	30		
	$t_{PLH}$	A or B	—	18	30		
	$t_{PHL}$		—	18	30		

Note: Refer to Test Circuit and Waveform of the Common Item "TTL Common Matter (Document No.: REJ27D0005-0100)".

Package Dimensions

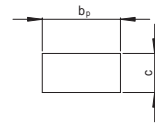
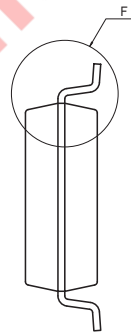
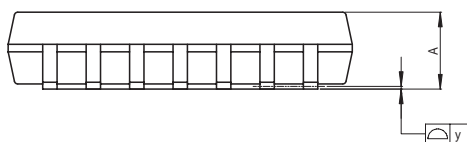
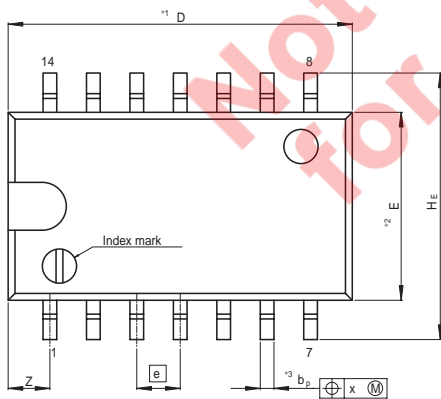
JEITA Package Code P-DIP14-6.3x19.2-2.54	RENESAS Code PRDP0014AB-B	Previous Code DP-14AV	MASS[Typ.] 0.97g
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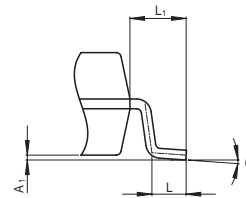
( Ni/Pd/Au plating )

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
e <sub>1</sub>	—	7.62	—
D	—	19.2	20.32
E	—	6.3	7.4
A	—	—	5.06
A <sub>1</sub>	0.51	—	—
b <sub>p</sub>	0.40	0.48	0.56
b <sub>3</sub>	—	1.30	—
c	0.19	0.25	0.31
θ	0°	—	15°
e	2.29	2.54	2.79
Z	—	—	2.39
L	2.54	—	—

JEITA Package Code P-SOP14-5.5x10.06-1.27	RENESAS Code PRSP0014DF-B	Previous Code FP-14DAV	MASS[Typ.] 0.23g
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Terminal cross section  
( Ni/Pd/Au plating )



Detail F

NOTE)  
1. DIMENSIONS\*1 (Nom)\*AND\*2\*  
DO NOT INCLUDE MOLD FLASH.  
2. DIMENSION\*3\*DOES NOT  
INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	10.06	10.5
E	—	5.50	—
A <sub>2</sub>	—	—	—
A <sub>1</sub>	0.00	0.10	0.20
A	—	—	2.20
b <sub>p</sub>	0.34	0.40	0.46
b <sub>1</sub>	—	—	—
c	0.15	0.20	0.25
c <sub>1</sub>	—	—	—
θ	0°	—	8°
H <sub>E</sub>	7.50	7.80	8.00
e	—	1.27	—
x	—	—	0.12
y	—	—	0.15
Z	—	—	1.42
L	0.50	0.70	0.90
L <sub>1</sub>	—	1.15	—

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